IPC-D-620

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Design and Critical Process Requirements for Cable and Wiring Harnesses

A standard developed by IPC

Association Connecting Electronics Industries

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Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
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- Increase cycle time
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- Contain anything that cannot be defended with data

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Developed by the Wire Harness Design Task Group (7-31k) and IPC-HDBK-620 Handbook Task Group (7-31h) of the Product Assurance Committee (7-30) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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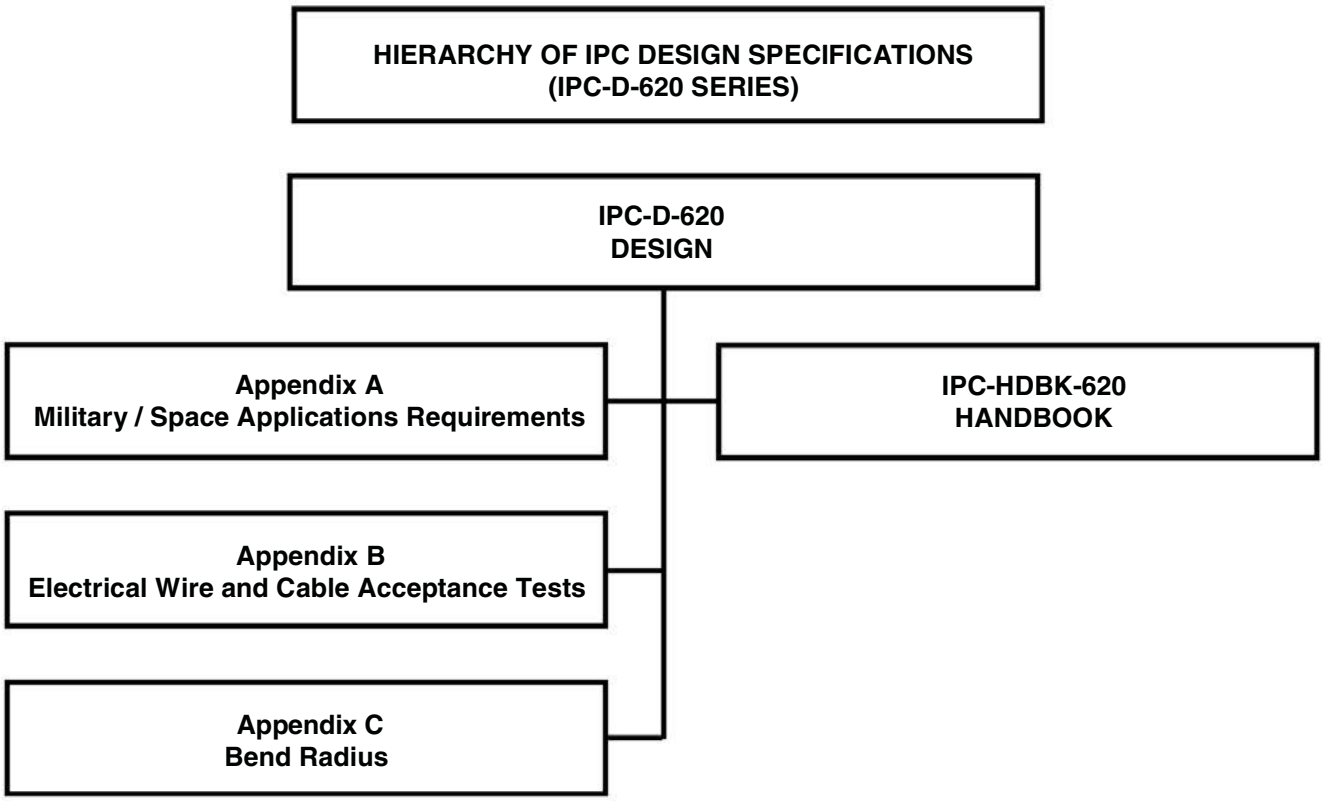

FOREWORD

This standard is intended to provide information on the design requirements for cable and wiring harness design, to the extent that they can be applied to the broad spectrum of cable and wiring harness design.

It is therefore crucial that decisions concerning the choice of product classification, wiring technology, connectorization requirements, and performance and reliability requirements be made as early as possible.

IPC-D-620 is supplemented by Appendices A-C and a handbook (IPC-HDBK-620), which provide the engineering rationale and technical guidance on cable and wiring harness design. The User needs, as a minimum, the Design Requirements document (IPC-D-620), and the engineering description of the final product.

As wiring and connector technology changes, specific requirements will be updated or new requirements added to the document set.

The IPC invites input on the effectiveness of the documentation and encourages User response through

The IPC invites input on the effectiveness of the documentation and encourages User response through completion of ''Suggestions for Improvement'' forms located at the end of each document.

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